

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHOON HEUNG LEE	05/10/2016
RECEIVING PARTY DATA	
Name:	AMKOR TECHNOLOGY, INC.
Street Address:	2045 E. INNOVATION CIRCLE
City:	TEMPE
State/Country:	ARIZONA
Postal Code:	85284
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15133081
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	602-326-2244
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ATTORNEY DOCKET NUMBER:	JK-020
NAME OF SUBMITTER:	KEVIN B. JACKSON
SIGNATURE:	/KEVIN B JACKSON/
DATE SIGNED:	05/10/2016
Total Attachments: 3	
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source=JK-020_Assignment_CH_Lee_executed_assignment_file#page3.tif	

ASSIGNMENT & AGREEMENT

JK-020

For good and valuable consideration, the receipt of which is hereby acknowledged, we,

Won Bae Bang	of Gyeonggi-do, Republic of Korea
Ju Hoon Yoon	of Gyeonggi-do, Republic of Korea
Ji Young Chung	of Gyeonggi-do, Republic of Korea
Byong Jin Kim	of Gyeonggi-do, Republic of Korea
Gi Jeong Kim	of Gyeonggi-do, Republic of Korea
Choon Heung Lee	of Seoul, Republic of Korea

have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto Amkor Technology, Inc. ("AMKOR") a Delaware corporation, having place of business at 2045 E. Innovation Circle, City of Tempe, State of Arizona, 85284, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain inventions relating to improvements in

METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE HAVING A MULTI-LAYER MOLDED CONDUCTIVE SUBSTRATE AND STRUCTURE

Attorney Docket No. JK-020; Amkor Ref: 1512069-P201502-003US; U.S. Patent Application No. 15/133,081 described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by us, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation, or reissue thereof.

We hereby also sell, assign, and transfer unto AMKOR, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize AMKOR to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to AMKOR, for the sole use and behalf of AMKOR, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to AMKOR.

We agree that, when requested, we will, without charge to AMKOR, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in AMKOR, its successors, assigns, and legal representatives or nominees.

We covenant with AMKOR, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Executed this ____ day of _____, 2016

Won Bae Bang
(Full Name)

Witnessed by: _____
Signature

Date

Printed Name

Assignment & Agreement (Continued)

Executed this ____ day of _____, 2016

Ju Hoon Yoon
(Full Name)

Witnessed by: _____

Signature

Date

Printed Name

Executed this ____ day of _____, 2016

Ji Young Chung
(Full Name)

Witnessed by: _____

Signature

Date

Printed Name

Executed this ____ day of _____, 2016

Byong Jin Kim
(Full Name)

Witnessed by: _____

Signature

Date

Printed Name

ASSIGNMENT & AGREEMENT

JK-020

Amkor Ref: 1512069-P201502-003US

Assignment & Agreement (Continued)

Executed this _____ day of _____, 2016

Gi Jeong Kim
(Full Name)

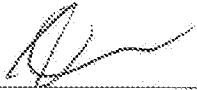
Witnessed by: _____

Signature _____

Date _____

Printed Name _____

Executed this 10 day of May, 2016



Choon Heung Lee
(Full Name)

Witnessed by: _____

Signature _____

Date _____

Printed Name _____

May 10, 2016

Myeong Heun, Lee